HLMP-N305, HLMP-NG0x, HLMP-NL06

T-1 (3 mm) Auto Insertable LED Lamps

Data Sheet



Description

This family of 3 mm LED Lamps is capable of withstanding automatic insertion and wave soldering processes.

Designed with a thick epoxy flange and soft leadframe material, it is ideal for clinch and cut operations.

Applications

- General purpose
- High volume manufacturing

Features

- T-1 (3 mm) auto-insertable package
- High brightness light output
- Tinted non-diffused lens
- Wide viewing angle
- Available colors: Red, Amber and Yellow
- Available with straight or formed lead tape and reel options

Device Selection Guide

High Brightness Lamps

Part Number	Color	Package lens	Luminous Intensity, Min. Iv @ 20 mA	Viewing Angle, 2θ _{1/2}	Package Drawing
HLMP-NG05	AlInGaP Red	Micro-tinted	90.2	45°	А
HLMP-NG07	AlInGaP Red	Micro-tinted	90.2	60°	В
HLMP-NL06	AlInGaP Amber	Micro-tinted	96.2	60°	В

High Efficiency Lamps

Part Number	Color	Package lens	Luminous Intensity, Min. Iv @ 10 mA	Viewing Angle, 2θ _{1/2}	Package Drawing
HLMP-N305	GaP Yellow	Tinted	14.7	45°	А

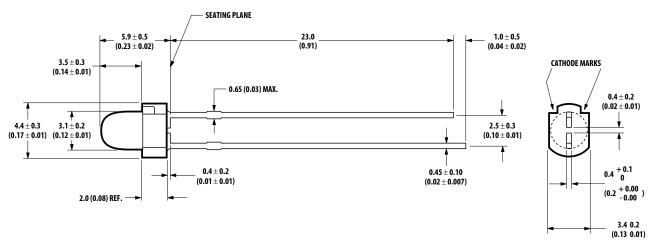
Note:

1. $2\theta^{1/2}$ is the off axis angle where the luminous intensity is $^{1/2}$ the on axis intensity.

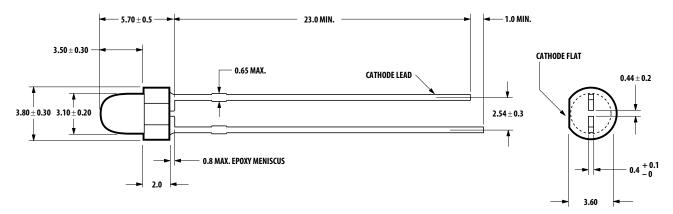


Package Dimensions

Package Drawing "A"



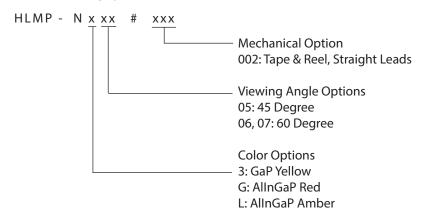
Package Drawing "B"



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Leads are mild steel with tin plating.
- 3. Epoxy meniscus of 0.8 mm (0.03 in.) Maximum may extend to the leads.
- 4. For PCB hole recommendations, see the Precautions section.

Part Numbering System



Absolute Maximum Ratings at T_A = 25 °C

		AlinGaP	
Parameter	Yellow	Amber & Red	Units
DC Forward Current ^[1]	20	30[2,3]	mA
Reverse Voltage (Ir = 100 µA)	5		V
Junction Temperature, T _{jmax}	110		°C
Storage Temperature Range	-40 to +85		°C
Operating Temperature Range	-20 to +85	-40 to +85	°C

Notes:

1. See Figure 4 for maximum current derating vs. ambient temperature.

2. Suggested minimum DC current: 10 mA.

3. Maximum Peak Pulsed Forward Current: 50 mA, 30 mA average.

Electrical Characteristics at T_A = 25°C

	Forward V	oltage Vf (Volts)	Capacitance C (pF) , Vf = 0, f = 1 MHz	Thermal Resistance R⊖ _{J-PIN}	Speed of Response $ au_{s}$ (ns) Time Constant e ^{-t} / $ au_{s}$
Part Number	Тур.	Max.	lf (mA)	Тур.	(°C/W)	Тур.
HLMP-N305	2.00	2.6	10	15	290	90
HLMP-NL06 ^[1]	2.02	2.4	20	40	240	20
HLMP-NG0x ^[1]	1.90	2.4	20	40	240	20

Note:

1. Please contact your Avago Sales Representative about operating currents below 10 mA.

Optical Characteristics at $T_A = 25 \text{ °C}$

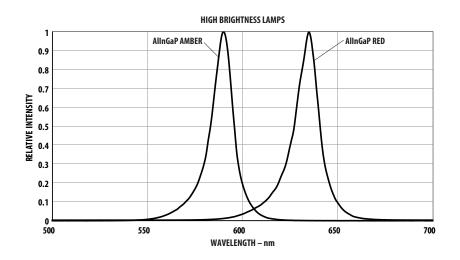
	Luminous Int	tensity ^[1]	Typ. Peak	Typ. Dominant Wavelength ^[2]	Typ. Spectral Half Width	Luminous Efficacy ^[3]
Part Number	Min. (mcd)	l _f (mA)	Wavelength (nm)	(nm)	(nm)	(Im/W)
HLMP-NG05	90.2	20	635	626	17	150
HLMP-NG07	90.2	20	635	626	17	150
HLMP-NL06	96.2	20	592	590	17	480
HLMP-N305	14.7	10	583	585	36	500

Notes:

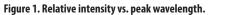
1. The luminous intensity, Iv, is measured at the mechanical axis of the lamp package. The actual peak of the spatial radiation pattern may not be aligned with this axis.

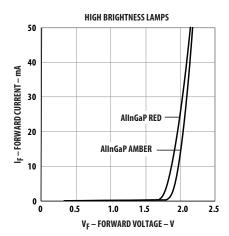
2. The dominant wavelength, λ_d , is derived from the CIE Chromaticity Diagram and represents the color of the device.

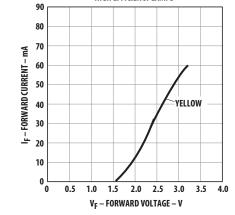
3. The radiant intensity, le, in watts per steradian, may be found from the equation $le = lv/\eta_v$, where lv is the luminous intensity in candelas and η_v is the luminous efficacy in lumens/watt.



HIGH EFFICIENCY LAMPS

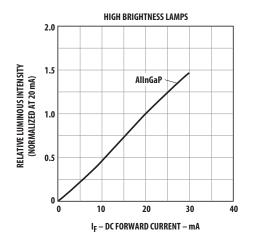






HIGH EFFICIENCY LAMPS

Figure 2. Forward current vs. forward voltage.



YELLOW

25

30

4.0 3.5

3.0

2.5

2.0 1.5

1.0 0.5

0

0

10

5

15

I_{DC} – DC CURRENT PER LED – mA

20

RELATIVE LUMINOUS INTENSITY (NORMALIZED AT 10 mA)

Figure 3. Relative luminous intensity vs. forward current.

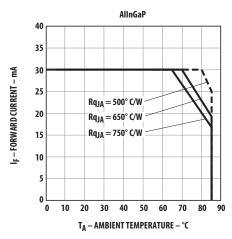


Figure 4. Maximum forward DC current vs. ambient temperature.

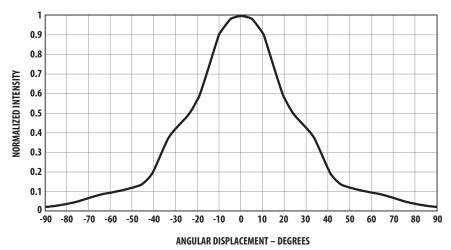


Figure 5. Representative spatial radiation pattern for 45° viewing angle.

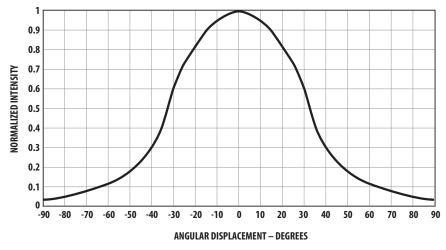


Figure 6. Representative spatial radiation pattern for 60° viewing angle.

Intensity Bin Limits

		Intensity Rang	
Color	Bin	Min.	Max.
	Н	13.8	27.6
	1	22.0	44.0
	J	35.2	70.4
	К	56.4	112.8
	L	90.2	180.4
	Μ	138.0	276.0
	Ν	200.0	400.0
	0	290.0	580.0
Red/Orange	Р	500.0	1000.0
/Red-Orange	Q	700.0	1400.0
	R	1000.0	2000.0
	S	1400.0	2800.0
	Т	2000.0	4000.0
	U	2900.0	5800.0
	V	4200.0	8400.0
	W	6000.0	12000.0
	Х	8700.0	17400.0
	Y	12600.0	25200.0
	Z	18200.0	36400.0
	G	14.7	29.4
	Н	23.5	47.0
	I	37.6	75.2
	J	60.1	120.2
	K	96.2	192.4
	L	147.0	294.0
	М	212.0	424.0
Yellow/Amber	N	300.0	600.0
	0	450.0	900.0
	Р	700.0	1400.0
	Q	1000.0	2000.0
	R	1600.0	3200.0
	S	2600.0	5200.0
	Т	4000.0	8000.0
	U	6500.0	13000.0
	V	10000.0	20000.0
	W	16000.0	30000.0

Amber Color Bin Limits

(nm at 20 mA)

Bin Name	Min.	Max.
1	584.5	587.0
2	587.0	589.5
4	589.5	592.0
6	592.0	594.5

Tolerance for each bin limit is ±0.5 nm.

Maximum tolerance for each bin limit is $\pm 18\%$.

Color Categories

Category #	Lambda (nm) Min.	Max.
1	582.0	584.5
3	584.5	587.0
2	587.0	589.5
4	589.5	592.0
5	592.0	593.0
	1 3 2	Category # Min. 1 582.0 3 584.5 2 587.0 4 589.5

Tolerance for each bin limit is ± 0.5 nm.

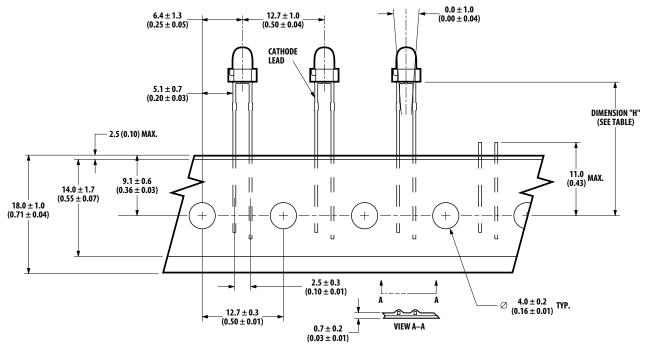
Taping Options

		Straight Lead	
Option	#002	#2CA	#2 CD
Dimension "B"	-	-	-
Dimension "H"	20.5 ± 1.0 (0.81 ± 0.04)	18.0 ± 1.0 (0.71 ± 0.04)	20.5 ± 1.0 (0.81 ± 0.04)

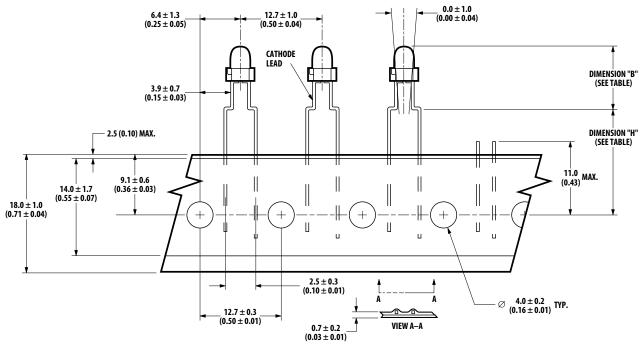
				ormed Lead			
Option	#2UK	#2UL	#2UM	#2UN	#2UP	#2UQ	#2UR
Dimension "B"	12.0 ± 1.0 (0.47 ± 0.04)	9.0 ± 1.0 (0.35 ± 0.04)	10.0 ± 1.0 (0.39 ± 0.04)	11.0 ± 1.0 (0.43 ± 0.04)	13.0 ± 1.0 (0.51 ± 0.04)	14.0 ± 1.0 (0.55 ± 0.04)	15.0 ± 1.0 (0.59 ± 0.04)
Dimension "H"				16.0 ± 1.0 (0.63 ± 0.04)			

Units: mm (inches)

Tape Outline Drawing



Straight Lead



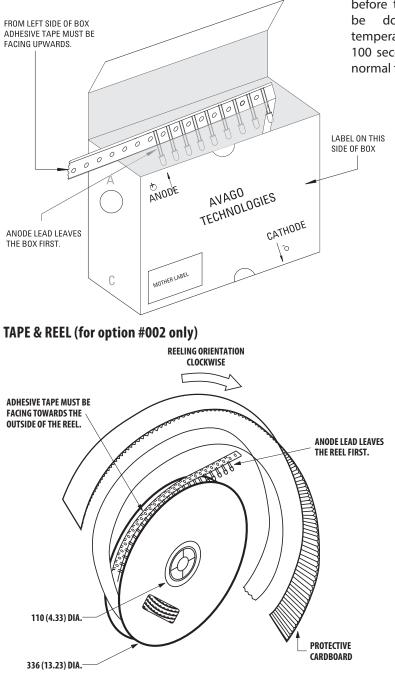
Formed Lead

Note: Dimension in mm (inches).

Package Options

Lead Option	Ammo Pack (1000 pcs.)	Tape & Reel (2000 pcs.)
Straight Lead	#2C —	#002
Formed Lead	#2U —	-

AMMO PACK (for All options except #002)



Recommended Assembly Condition

- A single-sided phenolic printed circuit board (PCB) is preferred. Double-sided PCB and other materials may cause greater lead stress. Recommended through-hole diameter is 0.98 to 1.08 mm. Leadlength below the PCB should be 1.5 to 2.0 mm, and the clinching angle (angle between the lead and PCB) should be 30 ±10 degrees.
- If SMT devices and an adhesive are used on the same pcb as these lamps, the adhesive should be cured before the lamps are auto-inserted. If curing must be done after lamp insertion, the cure temperature and time should not exceed 140°C, 100 seconds. This is the temperature of the surface normal to the IR source.

DIMENSIONS IN MILLIMETERS (INCHES).

Precautions

Lead Forming

- The leads of an LED lamp may be preformed or cut to length prior to insertion and soldering into PC board.
- If lead forming is required before soldering, care must be taken to avoid any excessive mechanical stress induced to LED package. Otherwise, cut the leads of LED to length after soldering process at room temperature. The solder joint formed will absorb the mechanical stress of the lead cutting from traveling to the LED chip die attach and wirebond.
- It is recommended that tooling made to precisely form and cut the leads to length rather than rely upon hand operation.

Soldering Conditions

- Care must be taken during PCB assembly and soldering process to prevent damage to LED component.
- The closest LED is allowed to solder on board is 1.59 mm below the body (encapsulant epoxy) for those parts without standoff.
- Recommended soldering conditions:

Dipping	Manual Solder
105 °C Max.	_
30 sec Max.	_
250 °C Max.	260 °C Max.
3 sec Max.	5 sec Max.
	105 °C Max. 30 sec Max. 250 °C Max.

- Wave soldering parameter must be set and maintained according to recommended temperature and dwell time in the solder wave. Customer is advised to periodically check on the soldering profile to ensure the soldering profile used is always conforming to recommended soldering condition.
- If necessary, use fixture to hold the LED component in proper orientation with respect to the PCB during soldering process.
- Proper handling is imperative to avoid excessive thermal stresses to LED components when heated. Therefore, the soldered PCB must be allowed to cool to room temperature, 25°C, before handling.
- Special attention must be given to board fabrication, solder masking, surface plating and lead holes size and component orientation to assure solderability.
- Recommended PC board plated through hole sizes for LED component leads:

	LED Component Lead Size	Diagonal	Plated Through -Hole Diameter
Lead size (typ.)	0.45 × 0.45 mm (0.018 × 0.018 in.)	0.636 mm (0.025 in)	0.98 to 1.08 mm (0.039 to 0.043 in) _
Dambar shear- off area (max.)	0.65 mm (0.026 in)	0.919 mm (0.036 in)	
Lead size (typ.)	0.50 × 0.50 mm (0.020 × 0.020 in.)	0.707 mm (0.028 in)	1.05 to 1.15 mm (0.041 to 0.045 in)
Dambar shear- off area (max.)	0.70 mm (0.028 in)	0.99 mm (0.039 in)	-

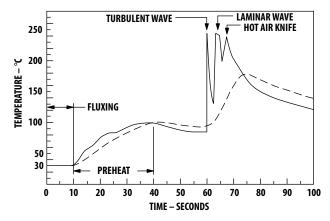


Figure 7. Recommended wave soldering profile.

Note: Refer to application note AN1027 for more information on soldering LED components.

— — TOP SIDE OF	 BOTTOM SIDE OF PC BOARD
I C DOAND	 TOP SIDE OF PC BOARD

CONVEYOR SPEED = 1.83 M/MIN (6 FT/MIN) PREHEAT SETTING = 150°C (100°C PCB) SOLDER WAVE TEMPERATURE = 245°C AIR KNIFE AIR TEMPERATURE = 390°C AIR KNIFE DISTANCE = 1.91 mm (0.25 IN.) AIR KNIFE ANGLE = 40 SOLDER: SN63; FLUX: RMA

NOTE: ALLOW FOR BOARDS TO BE SUFFICIENTLY COOLED BEFORE EXERTING MECHANICAL FORCE.

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